502700280 02/27/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2746885

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TSUTOMU TETSUKA	02/05/2014
MAKOTO SATAKE	02/05/2014
TADAYOSHI KAWAGUCHI	02/06/2014

RECEIVING PARTY DATA

Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION	
Street Address:	24-14, NISHI SHIMBASHI 1-CHOME, MINATO-KU	
City:	ТОКУО	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14181968

CORRESPONDENCE DATA

Fax Number: (703)610-8686 Phone: (703)903-9000

Email: ctexidor@milesstockbridge.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: MILES & STOCKBRIDGE P.C. Address Line 1: MITCHELL W. SHAPIRO

Address Line 2: 1751 PINNACLE DRIVE, SUITE 500
Address Line 4: TYSONS CORNER, VIRGINIA 22102-3833

ATTORNEY DOCKET NUMBER:	XA-12549/T3309-20419US01
NAME OF SUBMITTER:	MITCHELL W. SHAPIRO
Signature:	/Mitchell W. Shapiro/
Date:	02/27/2014

Total Attachments: 1

source=Assignment#page1.tif

PATENT REEL: 032318 FRAME: 0260

502700280

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation a corporation organized under the laws of Japan,

located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo, Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation its successor and assigns, all my right, title and interest, in and for the United States of America, in and to

PLASMA PROCESSING APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said. Hitachi High-Technologies Corporation.

its successor, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing. continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation

Signed on the date(s) indicated aside our signatures:

INIVENITOD(S)

	(発明者フルネームサイン)	(署名日)
1)_	Tsutama Tetsuka Tsutomu TETSUKA	2/5/2019
2)_	makata Sataka Makoto SATAKE	2/5/2014
3)_	Tadayoshi Kawaguchi Tadayoshi KAWAGUCHI	2/6 / 2014

PATENT

REEL: 032318 FRAME: 0261

Data Signad